

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,940,180 B1
APPLICATION NO. : 09/068270
DATED : September 6, 2005
INVENTOR(S) : Kenji Uchiyama

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title Page, References cited: under U.S. PATENT DOCUMENTS insert

-- 4,604,6448 (8/1986) Beckham et al. --
-- 5,187,123 (2/1993) Yoshida et al. --
-- 5,232,962 (8/1993) Dershem et al. --

under FOREIGN PATENT DOCUMENTS insert

-- EP 0 265 077 (1988) --
-- EP 0 517 071 A1 (1992) --

under OTHER PUBLICATIONS insert

-- Gilleo, K., "Direct Chip Interconnect Using Polymer Bonding", IEEE Transactions on Components, Hybrids and Manufacturing Technology, Vol 13, No. 1, 1 March 1990, pps 229-234 --
-- Jin, Sungho et al, "Anisotropically Conductive Polymer Films with a Uniform Dispersion of Particles", IEEE Transactions on Components, Hybrids and Manufacturing Technology, Vol. 16, No. 8, 1 December 1993, pps 972-977 --

Signed and Sealed this

Sixteenth Day of October, 2007



JON W. DUDAS
Director of the United States Patent and Trademark Office